

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A sol having a pH of 1 to 6 or 8 to 13 in which particles are dispersed in a medium, wherein the particles have a particle size of 50 to 150 nm and comprise as a main component crystalline cerium oxide of the cubic system and as an additional component a lanthanum compound, neodymium compound or a combination thereof, wherein the additional component is contained in $X/(Ce + X)$ molar ratio of 0.005 to 0.15 in which X is lanthanum atoms, neodymium atoms or a combination thereof.

2. (Original) A sol according to claim 1, wherein the additional component is a lanthanum compound.

3. (Original) A sol according to claim 1, wherein the additional component is a neodymium compound.

4-9. (Canceled)

10. (Currently Amended) An abrasive containing a sol having a pH of 1 to 6 or 8 to 13 in which particles are dispersed in an aqueous medium in a range of 0.1 to 50 wt%, wherein the particles have a particle size of 50 to 150 nm and comprise as a main component crystalline cerium oxide of the cubic system and as an additional component a lanthanum compound, neodymium compound or a combination thereof, wherein the additional component is contained in $X/(Ce + X)$ molar ratio of 0.005 to 0.15 in which X is lanthanum atoms, neodymium atoms or a combination thereof.

11. (Canceled)

12. (Previously Presented) An abrasive according to claim 10, wherein the additional component is a lanthanum compound.

13. (Previously Presented) An abrasive according to claim 10, wherein the additional component is a neodymium compound.
14. (Previously Presented) An abrasive according to claim 10, which is adjusted with an acidic substance to a pH of 1 to 6.
15. (Previously Presented) An abrasive according to claim 10, which is adjusted with a basic substance to a pH of 8 to 13.
16. (Previously Presented) An abrasive according to claim 10, which is used for polishing a substrate which comprises silica as a main component.
17. (Previously Presented) An abrasive according to claim 10, which is used for polishing a rock crystal, a quartz glass for photomask, a semiconductor device or a hard disk made of glass.
18. (Previously Presented) An abrasive according to claim 10, which is used in a step of polishing an organic film, a step of polishing Inter Layer Dielectric (ILD) or a step of shallow trench isolation, for polishing a semiconductor device.